

Bill of Materials

TI DESIGNS

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
!PCB	1		Printed Circuit Board		ISE4003	Any	-	-
C1	1	0.47uF	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E474KA12D	MuRata		
C2, C5, C6	3	0.1uF	CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0402	0402	GRM155R71C104KA88D	MuRata		
C3, C4, C7	3	1uF	CAP, CERM, 1uF, 16V, +/-10%, X7R, 0603	0603	GRM188R71C105KA12D	MuRata		
C8	1	100uF	CAP, CERM, 100uF, 10V, +/-20%, X5R, 1206_190	1206_190	C3216X5R1A107M160AC	TDK		
C10	1	33pF	CAP, CERM, 33pF, 50V, +/-5%, C0G/NP0, 0402	0402	GRM1555C1H330JA01D	MuRata		
C12	1	0.01uF	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0402	0402	GRM155R71C103KA01D	MuRata		
C13	1	1000pF	CAP, CERM, 1000pF, 16V, +/-10%, X7R, 0402	0402	GRM155R71C102KA01D	MuRata		
D1, D2	2	35V	Diode, Schottky, 35V, 0.1A, SOD-523F	SOD-523F	CDBU0130L	Comchip Technology		
D3	1	Orange	LED, Orange, SMD	1.6x0.8x0.8mm	SML-311DTT86	Rohm		
D4	1	Red	LED, Red, SMD	LED, 1.6x.8x.8mm	SML-311UTT86	Rohm		
J3	1		Receptacle, 6x1, 50mil, TH	Receptacle, 6x1, 50mil, TH	851-43-006-10-001000	Mill-Max		
R1, R4	2	0	RES, 0 ohm, 5%, 0.063W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale		
R2, R3	2	4.75k	RES, 4.75k ohm, 1%, 0.063W, 0402	0402	CRCW04024K75FKED	Vishay-Dale		
R5, R6	2	1.00k	RES, 1.00k ohm, 1%, 0.063W, 0402	0402	CRCW04021K00FKED	Vishay-Dale		
R7, R9	2	10.0k	RES, 10.0k ohm, 1%, 0.063W, 0402	0402	CRCW040210K0FKED	Vishay-Dale		
R8	1	47.5k	RES, 47.5k ohm, 1%, 0.063W, 0402	0402	CRCW040247K5FKED	Vishay-Dale		
U1	1		Mixed Signal Microcontroller, RGZ0048B	RGZ0048B	MSP430FR5969IRGZ	Texas Instruments		None

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U2	1		DYNAMIC NFC INTERFACE TRANSPONDER, PW0014A	PW0014A	RF430CL330HCPW	Texas Instruments		None
U3	1		Low-Power, Digital Temperature Sensor with Two-Wire Interface in WCSP, YFF0004AAAA	YFF0004AAAA	TMP103AYFF	Texas Instruments		None
U4, U5, U6, U7	4		ESD in 0402 Package	DPY0002A	TPD1E10B06DPYR	Texas Instruments	Equivalent	None
C9, C14	0		CAP, CERM, xxxF,	Used in PnP output	Used in BOM report	Used in BOM report	-	-
C11	0	39pF	CAP, CERM, 39pF,	0402	GRM1555C1H390JA01D	MuRata		
FID1, FID2, FID3, FID4, FID5, FID6	0		Fiducial mark. There	Fiducial	N/A	N/A		
J1	0		Header male, 2x1,	2x1 Header	GRPB021VWVN-RC	Sullins Connector Solutions		
J2	0		Header, 6x1, 50mil, TH	Header, 6x1, TH	GRPB061VWVN-RC	Sullins Connector Solutions		
J4, J5	0		Header, 1x1, Tin, TH	Header, 1x1, 50mil, TH	TMS-101-02-T-S	Samtec		

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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